

# Trusted Electronics

More Trust, Better Platforms

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1. Cybersicherheitstag, 9. November 2023, Fraunhofer AISEC



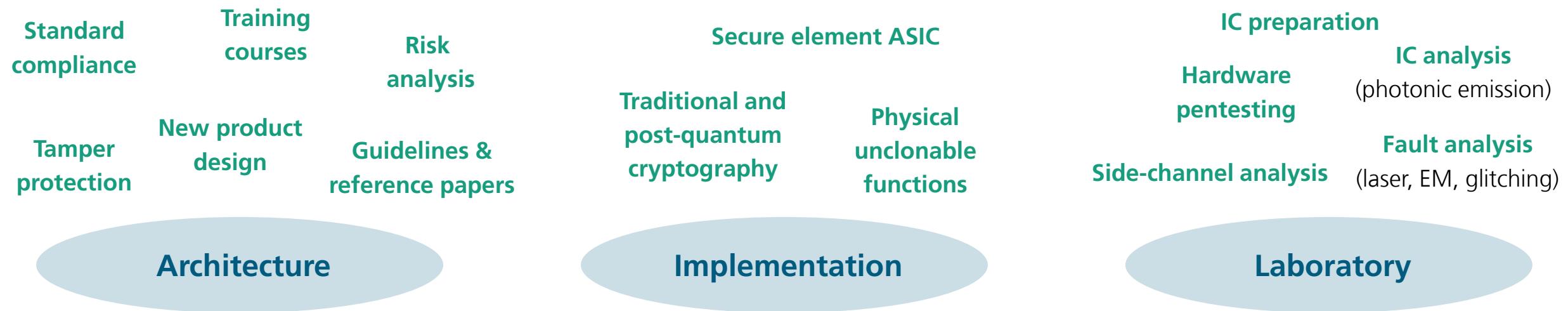
Fraunhofer-Institut für Angewandte  
und Integrierte Sicherheit AISEC

# Introduction

## Hardware Security Department

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- **About us**
  - 19 security researcher and 20+ students
  - Dr. Matthias Hiller, head of department
  - Dr. Nisha Jacob-Kabakci, head of PAC group
- **About me**
  - Head of *Secure Processor Platforms* group
  - Trusted electronics, RISC-V, open-source hardware
  - 10 years security engineering and research



# Motivation

What is trusted?<sup>1</sup>

## 1. High levels of quality and reliability.

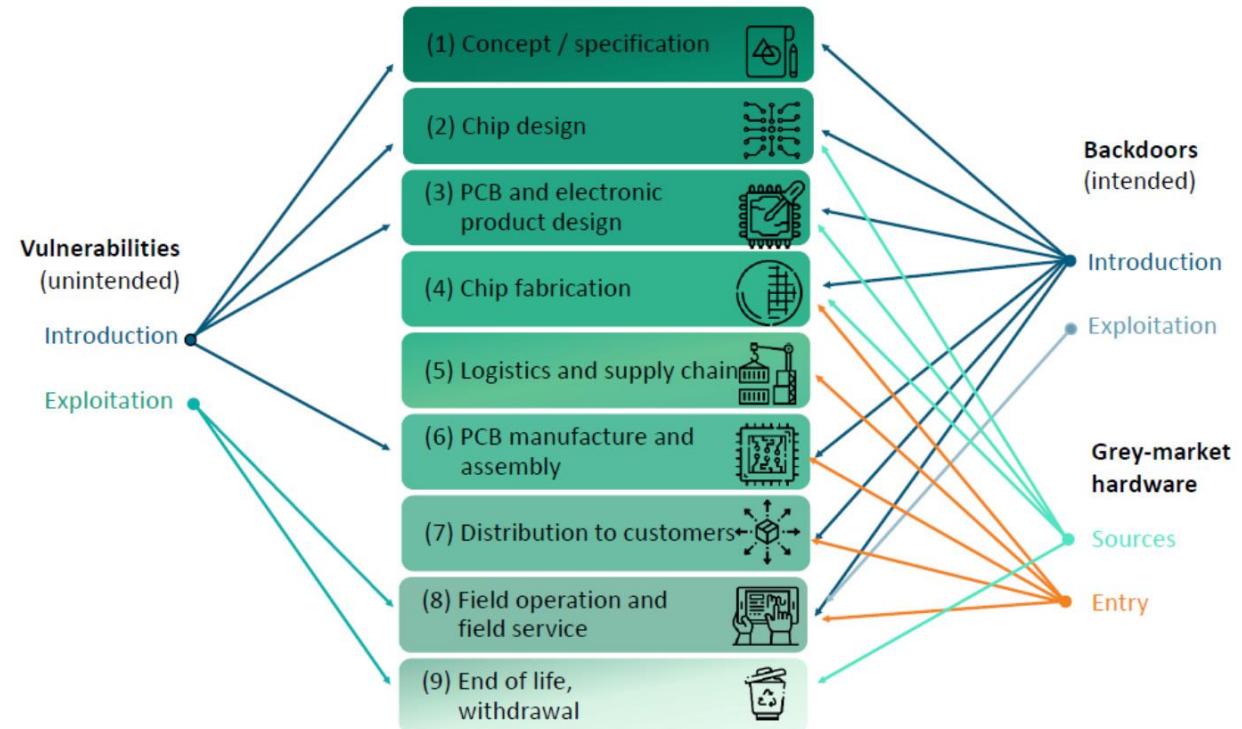
- Reliable operation of hardware in the field over its full lifetime.

## 2. Compliance to a known & complete specification.

- Functionality cannot be altered from the specification.

## 3. Hardened against state-of-the-art attacks.

- Mechanisms to ensure security and avoid vulnerabilities.



<sup>1</sup> VE-Velektronik reference paper: [DE](#) & [EN](#)  
[www.velektronik.de](http://www.velektronik.de)

# Motivation

## Open-source Hardware

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- **Links to trusted electronics**
  - Accessibility fosters innovation and competition (1)
  - Transparency enables traceability (2)
  - Community drives bug hunting (3)
- 
- **Our objectives**
  - Fraunhofer *next generation computing* agenda<sup>1</sup>
  - Relevant and visible research vehicles
  - Increased value creation for public funding

RISC-V  $\neq$  Open-source



<sup>1</sup> <https://www.fraunhofer.de/en/research/fraunhofer-strategic-research-fields.html>

# Motivation

## Project Landscape

- **VE-Velektronik<sup>1</sup>**

- BMBF project as part of ZEUS<sup>2</sup> call
- 2021 – 2024, 15 partner (Fraunhofer, Leibnitz, edacentrum)
- Reference paper on trusted electronics
  - Unintentional bugs in early design steps
  - Grey market hardware (overproduction, use of rejects)
  - Intentional manipulation in late value chain steps



- **Study for EU commission upcoming!**

- **Bavarian funding initiatives (85+ Mio. €)**

- **Trusted Electronic Bayern Center (TrEB)<sup>3</sup>**

- Hardware and system designs at IoT level
- Expansion of hardware security analysis laboratories

- **Bayerisches Chip-Design-Center (BCDC)<sup>4</sup>**

- Education and reduction of talent shortage
- Portfolio of hardware designs incl. ecosystem
- Accessibility to (low-volume) IC production

Gefördert durch



Bayerisches Staatsministerium für  
Wirtschaft, Landesentwicklung und Energie

<sup>1</sup><https://www.velektronik.de>

<sup>2</sup><https://www.elektronikforschung.de/foerderung/bekanntmachungen/zeus>

<sup>3</sup><https://www.aisec.fraunhofer.de/de/presse-und-veranstaltungen/pressemitteilungen/2022/mikroelektronik-forschung-in-bayern.html>

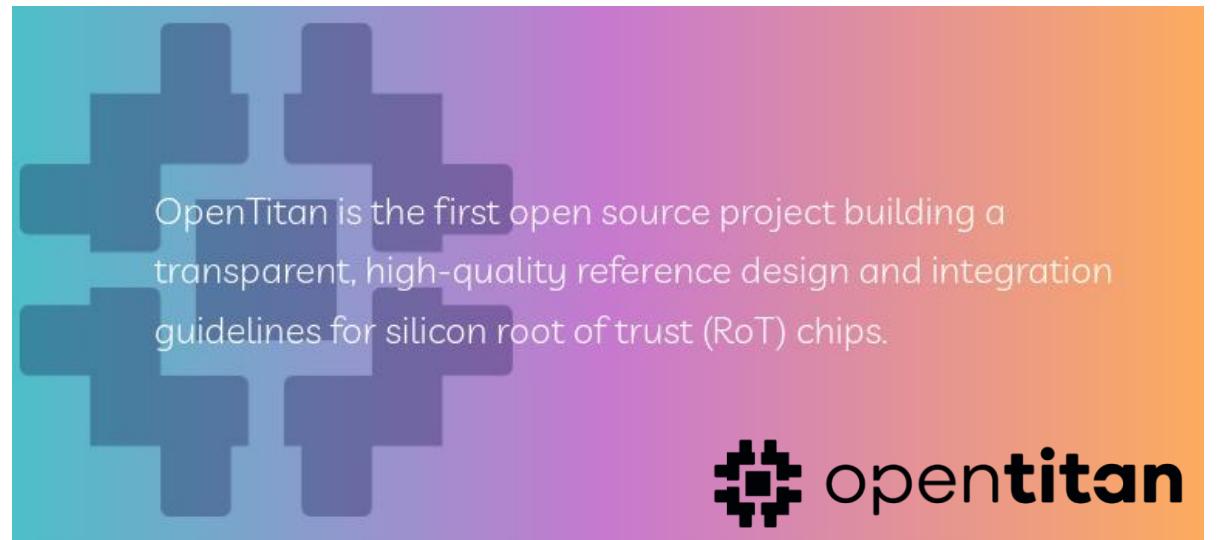
<sup>4</sup><https://www.iis.fraunhofer.de/de/ff/sse/bayerisches-chip-design-center.html>

# OpenTitan Project

## Overview

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- **OpenTitan project**<sup>1,2</sup>
- lowRISC, Google, ETH Zürich, G+D, Nuvoton, ...
- System-on-chip (SoC) for authentication and platform integrity
- µC range: Ibex 32-bit (“zero-riscy”) RISC-V core
- **Our motivation**
- Research on a *real-world*, security-focused µC platform
- Increasing accessibility to secure and affordable hardware
- **Our relation to the project**
- Project user since end of 2019
- Not part of the consortium



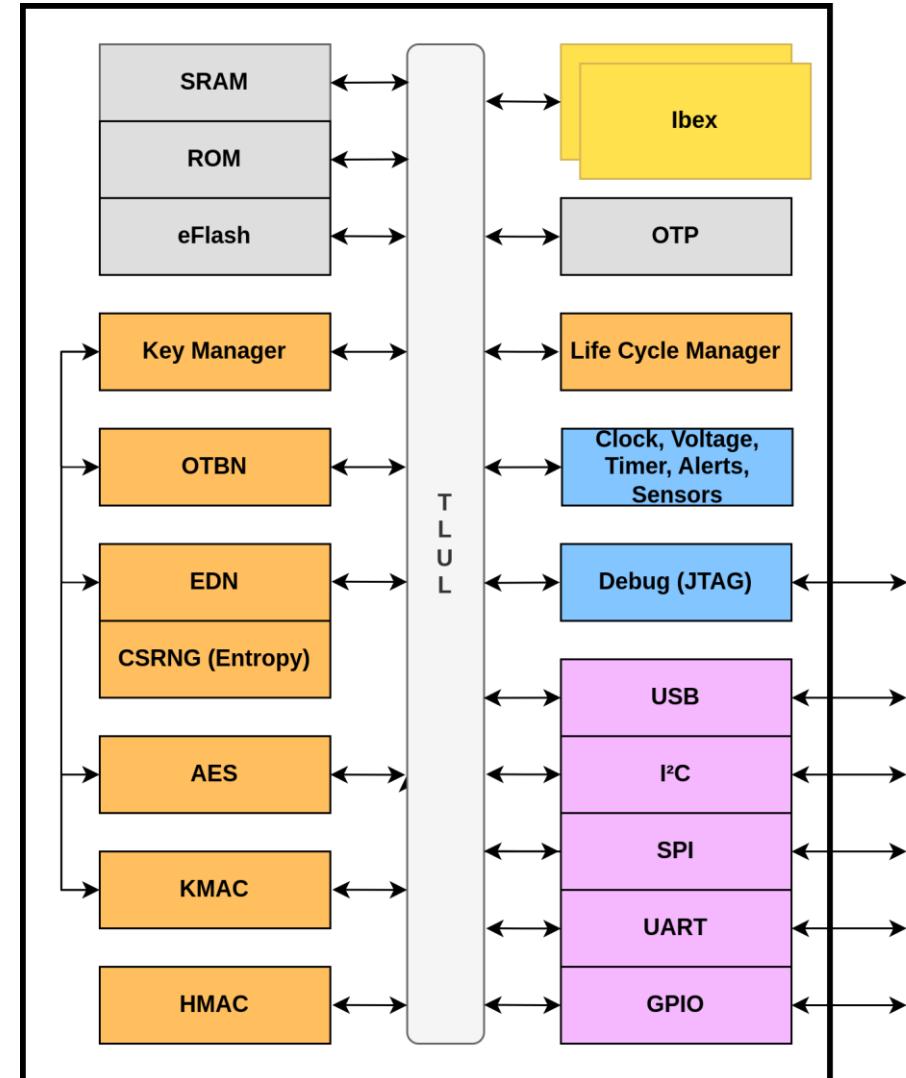
<sup>1</sup> <https://opentitan.org/>

<sup>2</sup> <https://github.com/lowRISC/opentitan>

# OpenTitan Project

## Properties

- ***Earl Grey top-level design***<sup>1</sup>
- 100 MHz, 32-bit, 3-stage, dual-core lockstep CPU
- eFlash, SRAM, ROM, OTP (all scrambled)
- AES, SHA-2/3, RSA, ECC, CSRNG (with selected countermeasures)
- Lifecycles, key manager, attestation, secure boot & update
- **Use-cases**<sup>2</sup>
- Platform integrity module
- Trusted platform module
- Universal 2nd-factor security key



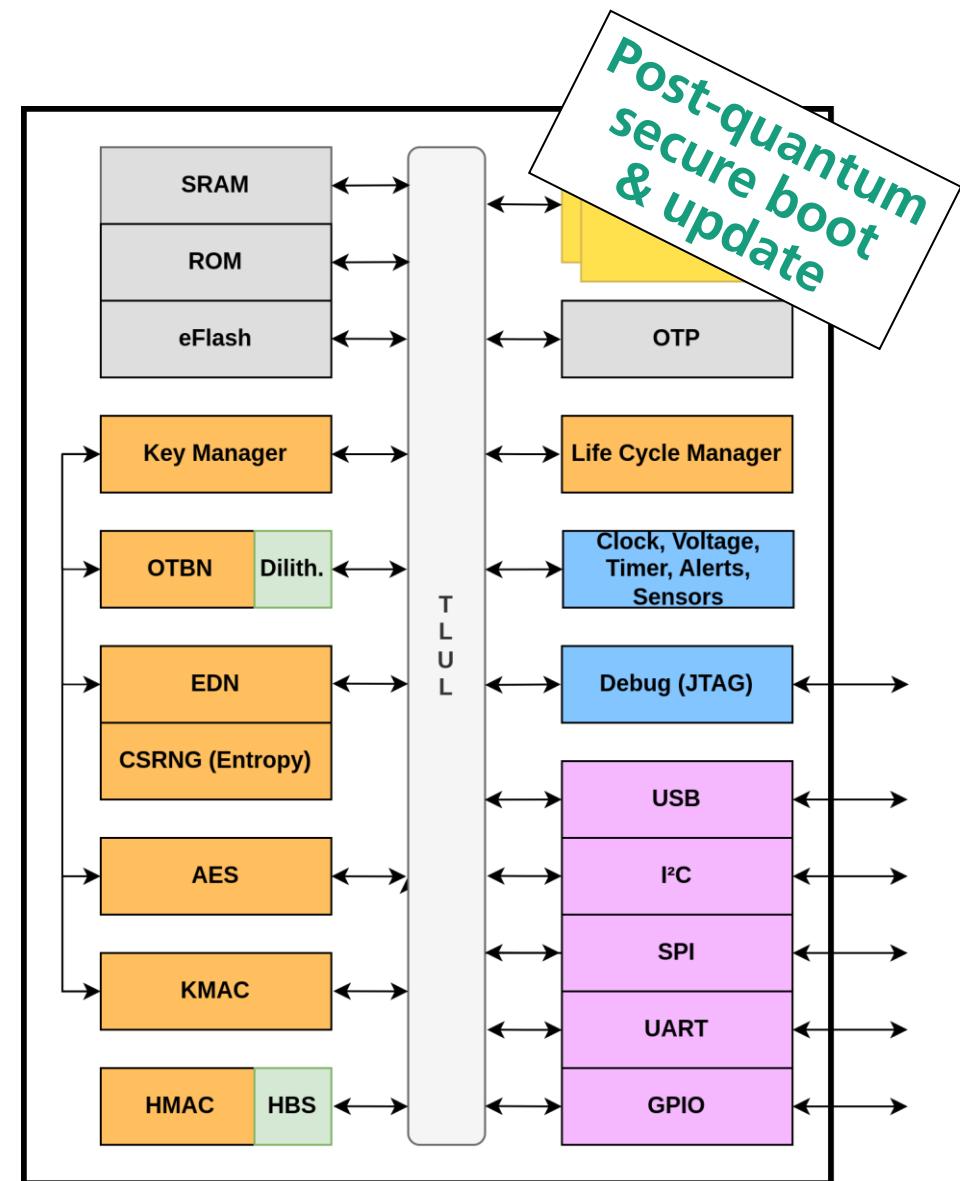
<sup>1</sup> [https://opentitan.org/book/hw/top\\_earlgrey/doc/specification.html](https://opentitan.org/book/hw/top_earlgrey/doc/specification.html)

<sup>2</sup> [https://opentitan.org/book/doc/use\\_cases/index.html](https://opentitan.org/book/doc/use_cases/index.html)

# OpenTitan Project

## Extensions

- Hash-based signature extension to HMAC / SHA-2 core <sup>1</sup>
- LMS, XMSS, SPHINCS+
- 56 kGE (HMAC) + 11 kGE (LMS) + 6 kGE (SPX<sup>+-s</sup>)
- Signature size **1.6 kB** (LMS) and **29 kB** (SPX<sup>+-s</sup>)
- Public key size **32 bytes** (LMS) and **64 bytes** (SPX<sup>+-s</sup>)
- Signature verification in **10 ms** (LMS) and **50 ms** (SPX<sup>+-s</sup>)
- CRYSTALS-Dilithium extension to OTBN <sup>2</sup>
- Instruction set extensions for polynomial arithmetic and sampling
- 4711 kGE (OpenTitan) + 242 kGE (Dilithium)
- Signature size **4.6 kB**, public key size **2.6 kB**
- Signature verification in **22 ms**



<sup>1</sup> A. Wagner, F. Oberhansl, M. Schink: <https://doi.org/10.1145/3560834.3563831>

<sup>2</sup> T. Stelzer, F. Oberhansl, J. Schupp, P. Karl: Accepted at ASIES 2023, 30. November, Copenhagen, <http://ashesworkshop.org/>

# Security Assessment

## Analysis in the Laboratory

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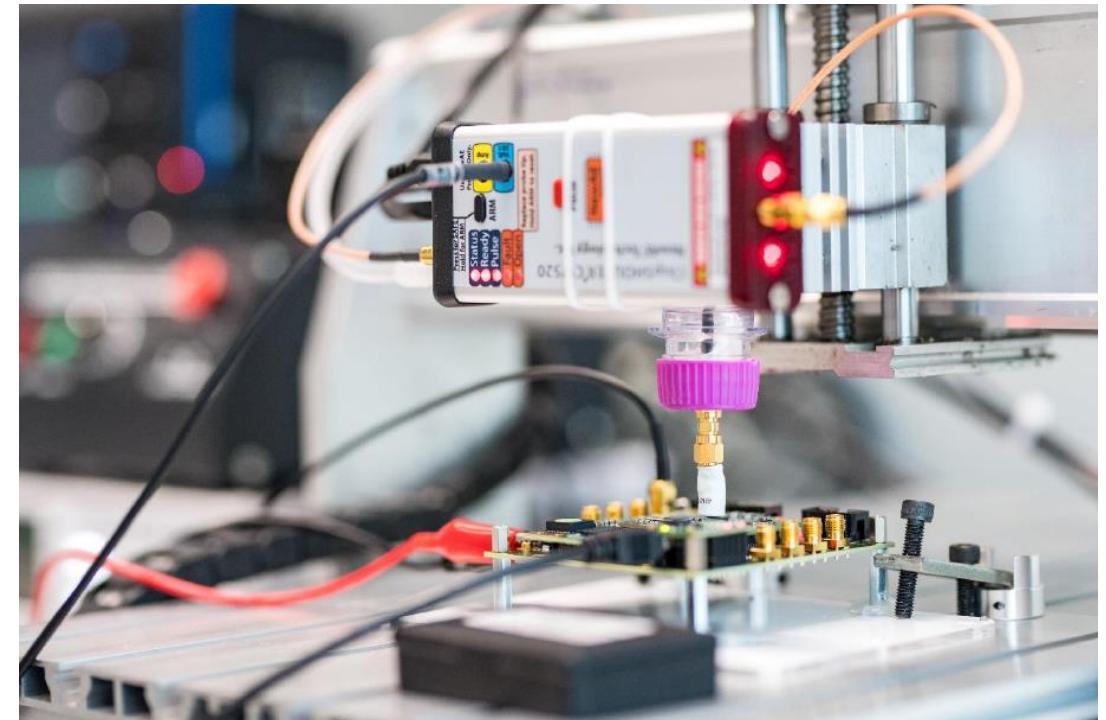
- **Analysis at AISEC**
  - Power- and EM-based side-channel analysis
  - Fault injection: laser, EM, glitching
  - Invasive IC analysis
    - Decapsulation, etching
    - Electro Optical Probing (EOP)
    - Thermal laser stimulation (TLS)
- **Analysis at FhG**
  - Advanced decapsulation, etching, delayering
  - Advanced imaging capabilities
    - e.g., scanning electron microscopy
- **Common Criteria site-certification ongoing**



# Security Assessment

## Hardware Attacks against µC

- ***Study on Hardware Attacks against Microcontrollers<sup>1</sup>***
- On behalf of the German Federal Office for Information Security (BSI)
- **µC in security-relevant products**
- Hardware security keys
- Hardware crypto wallets
- Smart locks
- Point-of-sales terminals
- **Threats from:** supply chain, evil maid, device theft
- **Attacks** (control-flow manipulation, side-channel analysis, read-out protection bypass) and **countermeasures** (check out the study!)



<sup>1</sup> M. Schink, F. Oberhansl, A. Wagner, K. Zinnecker, A. Garcia: [https://www.bsi.bund.de/DE/Service-Navi/Publikationen/Studien/Hardware-Angriffe/Hardware-Angriffe\\_node.html](https://www.bsi.bund.de/DE/Service-Navi/Publikationen/Studien/Hardware-Angriffe/Hardware-Angriffe_node.html)

# Security Assessment

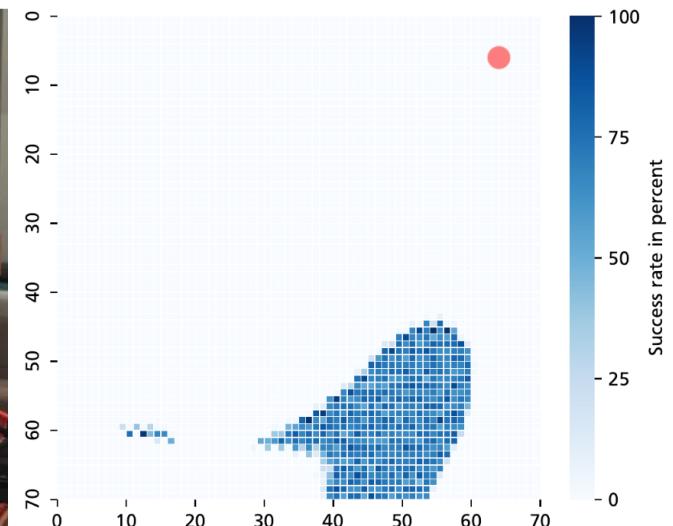
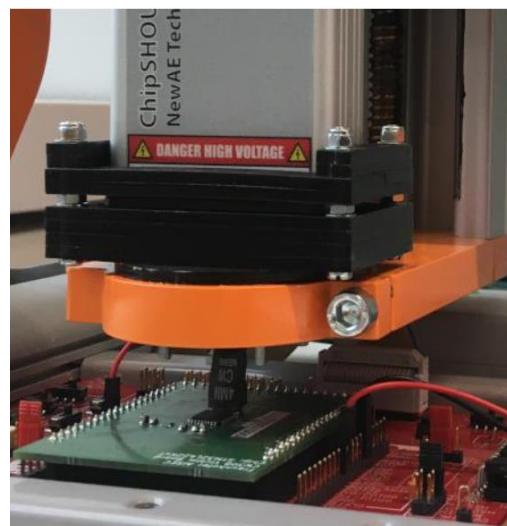
## Findings

- **Successful attacks**

- Debug unlock with flash erase suppression possible with EM fault injection → check for blank flash or sense EM pulses
- Secure boot bypass with single-instruction-skip through EM fault injection (MCUboot and mbedTLS) → redundant execution

- **Status Quo**

- Many security-relevant products are built based on COTS µC with no focus on security or no certification
- Lack of
  - ... support for developers
  - ... security documentation
  - ... thorough reviews and testing



# Conclusion

What's now, what's next?

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- **Increased trust in electronics**

- Complex and international value chain
- RISC-V and open-source hardware can help
- It's a joint effort, so feel free to get in touch

- **New collaborative platforms?**

- Shared effort and shared cost
- Adequate and affordable security
- Broad application → high impact

- **Tag der vertrauenswürdigen Elektronik (TdvE)**

- 04. and 05. June 2024, Munich
- Connecting science, industry, government
- Organized by Fraunhofer EMFT and AISEC

- **Trusted Chips Kick-off <sup>1</sup>**

- 13. November 2023, Frankfurt & online
- Standardization needs & recommendations
- Coordinated by DKE, funded by EU

<sup>1</sup> <https://www.dke.de/en/veranstaltungs-detaillseite?id=22221&type=vde%7Cvdb>

# Thank you for your attention

Andreas Seelos-Zankl  
**Head of Research Group**  
**Secure Processor Platforms**  
**Hardware Security Department**  
[andreas.zankl@aisec.fraunhofer.de](mailto:andreas.zankl@aisec.fraunhofer.de)

Fraunhofer Institute for Applied and Integrated Security (AISEC)  
Lichtenbergstraße 11  
85748 Garching  
[www.aisec.fraunhofer.de](http://www.aisec.fraunhofer.de)